

Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

/!\ REMINDERS

Product Information in this Catalog

Product information in this catalog is as of October 2019. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for generalpurpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment *1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *2

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
- (6) Military equipment
- (7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes:

- 1. There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement

■ TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

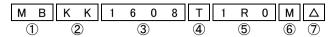
Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ MB SERIES)



PARTS NUMBER

* Operating Temp.:- $40\sim+105^{\circ}C$ (Including self-generated heat)



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$(1)S\epsilon$	eries	nan	ne

Code	Series name
MB	Metal Wire-Wound chip power inductor

4 Packaging Code

Code	Series name				
MB	Metal Wire-Wound chip power inductor				

3 Nominal Induct	ance
Code	Nominal inductance[μ H]
(example)	-, -
R24	0.24
1R0	1.0
4R7	4.7

Packaging Taping

②Dimensions(T)

Code	Dimensions(T)[mm]			
KK	1.0			
MK	1.2			

③Dimensions (L × W)

Code	Type (inch)	Dimensions (L×W) [mm]
1608	1608 (0603)	1.6 × 0.8
2012	2012 (0805)	2.0 × 1.25
2520	2520 (1008)	25×20

6 Inductance tol	erance
Code	Inductance tolerance
М	±20%
N	±30%

7Internal code

■STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY

Recommended Land Patterns

•Mounting and soldering conditions should be checked beforehand.

• Applicable soldering process to these products is reflow soldering only.



Туре	Α	В	С
1608	0.55	0.70	1.00
2012	0.60	1.00	1.45
2520	0.60	1.50	2.00

Unit:mm

Туре		W	Т		Standard quantity[pcs]		
	L	VV		е	Paper tape	Embossed tape	
MBKK1608	1.6±0.2	0.8 ± 0.2	1.0 max	0.45±0.15		3000	
MIDKKIOO	(0.063 ± 0.008)	(0.031 ± 0.008)	(0.040 max)	(0.016 ± 0.006)	_	3000	
MDKK3013	2.0±0.2	1.25±0.2	1.0 max	0.5±0.2		3000	
MBKK2012	(0.079 ± 0.008)	(0.049 ± 0.008)	(0.040 max)	(0.020 ± 0.008)	_		
MDMK0E00	2.5±0.2	2.0±0.2	1.2 max	0.5±0.2		2000	
MBMK2520	(0.098 ± 0.008)	(0.079 ± 0.008)	(0.047 max)	(0.020 ± 0.008)	_	3000	
Unit: mm (inch)							

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MBKK1608(0603) type	[Thickness: 1.0mm	max.]

		Managard Sadardana		Self-resonant	DO Decistance	Rated current ※) [mA](max.)		Managara
Parts number	EHS	Nominal inductance [μ H]			Saturation current Idc1	Temperature rise current Idc2	Measuring frequency[MHz]	
MBKK1608TR24N	RoHS	0.24	±30%	-	0.049	1,650	2,300	1.0
MBKK1608TR47N	RoHS	0.47	±30%	-	0.104	1,100	1,400	1.0
MBKK1608TR68N	RoHS	0.68	±30%	-	0.120	950	1,200	1.0
MBKK1608T1R0M	RoHS	1.0	±20%	-	0.150	800	1,150	1.0
MBKK1608T1R5M	RoHS	1.5	±20%	-	0.200	650	1,000	1.0
MBKK1608T2R2M	RoHS	2.2	±20%	-	0.345	520	750	1.0
MBKK1608T3R3M	RoHS	3.3	±20%	-	0.512	450	600	1.0
MBKK1608T4R7M	R₀HS	4.7	±20%	-	0.730	370	500	1.0

		Nominal inductance		Self-resonant	DC Resistance	Rated current	Measuring	
Parts number EHS Nominal inductance Inductance tolerance	frequency [Ω](max.)		Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]			
MBKK2012TR24N	RoHS	0.24	±30%	-	0.041	3,000	2,400	1.0
MBKK2012TR47N	RoHS	0.47	±30%	-	0.078	2,000	1,650	1.0
MBKK2012TR68N	RoHS	0.68	±30%	-	0.090	1,800	1,500	1.0
MBKK2012T1R0M	RoHS	1.0	±20%	-	0.106	1,500	1,450	1.0
MBKK2012T1R5M	RoHS	1.5	±20%	-	0.173	1,200	1,100	1.0
MBKK2012T2R2M	RoHS	2.2	±20%	1	0.290	900	850	1.0
MBKK2012T3R3M	RoHS	3.3	±20%	=	0.500	700	650	1.0
MBKK2012T4R7M	R ₀ HS	4.7	±20%	-	0.615	600	600	1.0

		N III .		Self-resonant	DC Resistance	Rated current	Measuring		
Parts number	EHS	Nominal inductance [μ H]	Inductance tolerance	frequency [MHz] (min.)	[Ω] (max.)	Saturation current Idc1	Temperature rise current Idc2	frequency[MHz]	
MBMK2520TR24N	RoHS	0.24	±30%	ı	0.026	4,750	3,500	1.0	
MBMK2520TR47N	RoHS	0.47	±30%	ı	0.042	3,900	2,600	1.0	
MBMK2520TR68N	RoHS	0.68	±30%	1	0.058	3,150	2,150	1.0	
MBMK2520T1R0M	RoHS	1.0	±20%	ı	0.072	2,350	1,850	1.0	
MBMK2520T1R5M	RoHS	1.5	±20%	ı	0.106	2,050	1,500	1.0	
MBMK2520T2R2M	RoHS	2.2	±20%	ı	0.159	1,800	1,250	1.0	
MBMK2520T3R3M	RoHS	3.3	±20%	ı	0.260	1,400	970	1.0	
MBMK2520T4R7M	RoHS	4.7	±20%	-	0.380	1,150	800	1.0	

- $\frak{\%}$) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)
- $\mbox{\%}$) The temperature rise current value (Idc2) is the DC current value having temperature increase by 40°C. (at 20°C)
- $\ensuremath{\ensuremath{\mathbb{X}}}\xspace)$ The rated current value is following either Idc1 or Idc2, which is the lower one.

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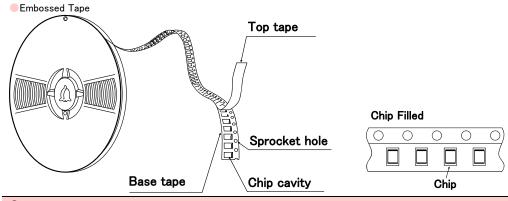
METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ MB SERIES / MCOIL™ MB-H SERIES)

■PACKAGING

1 Minimum Quantity

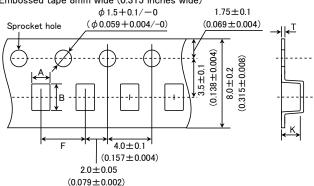
Type	Standard Quantity [pcs]
Туре	Tape & Reel
MBKK1608/MBKK1608H	3000
MBKK2012	3000
MBMK2520/MBMK2520H	3000

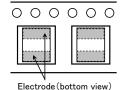
2Tape Material



3 Taping dimensions

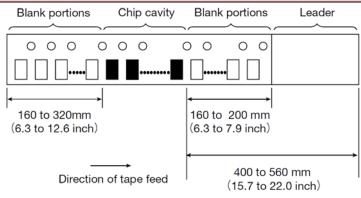
Embossed tape 8mm wide (0.315 inches wide)





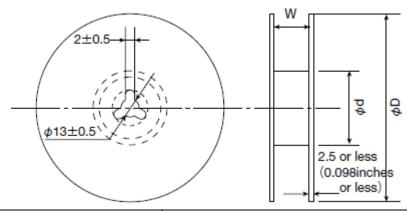
Tuna	Chip	cavity	Insertion pitch	Tape thickness	
Туре	Α	В	F	Т	K
MBKK1608 / MBKK1608H	1.1	1.9	4.0±0.1	0.25±0.05	1.2 max
MRKK1008/ MRKK1008H	(0.043)	(0.075)	(0.157 ± 0.004)	(0.010 ± 0.002)	(0.047 max)
MBKK2012	1.45	2.2	4.0±0.1	0.25±0.05	1.2 max
	(0.057)	(0.087)	(0.157 ± 0.004)	(0.010 ± 0.002)	(0.047 max)
MBMK2520/MBMK2520H	2.3	2.8	4.0±0.1	0.3±0.05	1.45 max
	(0.091)	(0.110)	(0.157 ± 0.004)	(0.012 ± 0.002)	(0.057 max)
					Unit:mm(inch)

4 Leader and Blank portion



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⑤Reel size

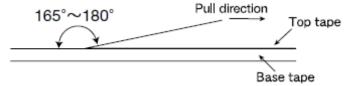


Type	Reel size (Reference values)				
Туре	ϕ D	ϕ d	W		
MBKK1608/MBKK1608H	180+0/-3	60+1/-0	10.0±1.5 (0.394±0.059)		
MBKK2012	(7.087+0/-0.118)	(2.36+0.039/0)			
MBMK2520/MBMK2520H	(7.067+0/-0.116)	(2.30+0.039/0)			

Unit:mm(inch)

6Top Tape Strength

The top The top tape requires a peel-off force of 0.2 to 0.7N in the direction of the arrow as illustrated below.



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METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ MB SERIES ✓ MCOIL™ MB-H SERIES)

Test Methods and

Remarks

Measuring equipment

RELIABILITY DATA 1. Operating Temperature Range -40~+105°C MB series Specified Value -40~+125°C MB-H series Test Methods and Including self-generated heat Remarks 2. Storage Temperature Range MB series -40~+85°C Specified Value MB-H series Test Methods and 0 to 40° C for the product with taping. Remarks 3. Rated current MB series Specified Value Within the specified tolerance MB-H series 4. Inductance MB series Specified Value Within the specified tolerance MB-H series Test Methods and : LCR Meter (HP 4285A or equivalent) Measuring equipment Remarks Measuring frequency : 1MHz, 1V 5. DC Resistance MB series Specified Value Within the specified tolerance MB-H series

6. Self resonance frequency				
Specified Value	MB series			
	MB-H series			

: DC ohmmeter (HIOKI 3227 or equivalent)

7. Temperature characteristic					
Specified Value	MB series	Inductance change : Within ±15%			
Specified Value	MB-H series	Inductance change : Within 110%			
Test Methods and	MB series: Measurement of inductance shall be taken at temperature range within $-40^{\circ}\text{C} \sim +105^{\circ}\text{C}$. With reference to inductance value at $+20^{\circ}\text{C}$, change rate shall be calculated.				
Remarks	MB-H series : Measurement of inductance shall be taken at With reference to inductance value at $\pm 20^{\circ}$ C				

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8. Resistance to flexure of substrate MB series Specified Value No damage MB-H series The test samples shall be soldered to the test board by the reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm. $: 100 \times 40 \times 1.0 \text{ mm} (1608:0.8 \text{mm})$ Test board size Test board material : Glass epoxy-resin Test Methods and Solder cream thickness : 0.1 mm Remarks Board 9. Insulation resistance : between wires MB series Specified Value MB-H series 10. Insulation resistance: between wire and core DC25V $100k\Omega$ min MB series Specified Value MB-H series DC50V $100k\Omega$ min 11. Withstanding voltage: between wire and core MB series Specified Value MB-H series 12. Adhesion of terminal electrode MB series Specified Value No abnormality. MB-H series The test samples shall be soldered to the test board by the reflow. Test Methods and Applied force : 10N (1608:5N) to X and Y directions. Remarks Duration : 5s. Solder cream thickness : 0.1mm 13. Resistance to vibration MB series Inductance change : Within $\pm 10\%$ Specified Value No significant abnormality in appearance. The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions. Frequency Range 10∼55Hz Total Amplitude 1.5mm (May not exceed acceleration 196m/s²) Test Methods and Sweeping Method 10Hz to 55Hz to 10Hz for 1min. Remarks Χ Υ Time For 2 hours on each X, Y, and Z axis. Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs. 14. Solderability MB series Specified Value At least 90% of surface of terminal electrode is covered by new solder. MB-H series The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux: Methanol solution containing rosin 25%. Solder Temperature 245±5°C Test Methods and Remarks Immersing speed 25mm/s Time 5 ± 0.5 sec.

XImmersion depth: All sides of mounting terminal shall be immersed.

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15. Resistance to soldering heat MB series Inductance change: Within ±10% Specified Value No significant abnormality in appearance. MB-H series The test sample shall be exposed to reflow oven at 230°C for 40 seconds, with peak temperature at 260 + 0/-5°C for 5 seconds, 3 times. Test Methods and Test board material : Glass epoxy-resin Remarks Test board thickness : 1.0mm Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

16. Thermal shock								
Specified Value	MB series			Inductance change : Within ±10%				
Specified Value	MB-H se	eries		No significant a	abnorma	ality in app	earance.	
		samples shall be soldered		-		MB-H series: The test samples s		
	The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.					-		
	Conditions of 1 cycle				Ī			
Test Methods and	Step	Temperature (°C)	Dur	ation (min)		Step	Temp	
Remarks	1	-40 ± 3		30±3		1	-	
	2	Room temperature	١	Within 3		2	Room	
	3	+85±2		30±3		3	+	
	4 Room temperature		١	Within 3		4	Room	
	Recovery : At least 2hrs of recovery under the standard condition Recovery : At						y : At leas	
	after the test, followed by the measurement within 48hrs.					after the test, follo		

MB-H series:

The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.

Conditions of 1 cycle						
Step	Temperature (°C)	Duration (min)				
1	-40±3	30±3				
2	Room temperature	Within 3				
3	+125±2	30±3				
4	Room temperature	Within 3				

Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

17. Damp heat						
C 'C 17/1	MB series		Inductance change : Within ±10%			
Specified Value	MB-H series		No significant abnormality in appearance.			
Test Methods and	MB series: The test samples shall be soldered to the test board by the re The test samples shall be placed in thermostatic oven se specified temperature and humidity as shown in below table.			The test samples	hall be soldered to the test shall be placed in therm are and humidity as shown i	ostatic oven set at
Remarks	Temperature	60±2°C		Temperature	85±2°C]
	Humidity	90∼95%RH		Humidity	85%RH	
	Time $1000+24/-0$ hour			Time	1000+24/-0 hour	
	Recovery: At least 2hrs of recovery under the standard condition			Recovery: At least 2hrs of recovery under the standard condition		
	after the test, followed by the measurement within 48hrs.			after the test, follo	wed by the measurement w	ithin 48hrs.

18. Loading under damp heat						
C:	MB series		Inductance change : Within ±10%			
Specified Value	MB-H series		No significant abnorm	ality in appearance.		
	MB series:			MB-H series:		
		all be soldered to the tes	•	· ·	all be soldered to the test	•
	· ·	shall be placed in thern		static oven set at The test samples shall be placed in thermosta		
	specified temperature	re and humidity and appl	ied the rated current	specified temperature and humidity and applied the rated currer		
Test Methods and	continuously as show	wn in below table.		continuously as shown in below table.		
Remarks	Temperature	60±2°C		Temperature	85±2°C	
	Humidity	90∼95%RH		Humidity	85%RH	
	Applied current	Rated current		Applied current	Rated current	
	Time	1000+24/-0 hour		Time	1000+24/-0 hour	
	Recovery : At least 2hrs of recovery under the standard condition			Recovery: At least 2hrs of recovery under the standard condition		
	after the test, followed by the measurement within 48hrs.			after the test, followed by the measurement within 48hrs.		

19. Low temperatur	19. Low temperature life test				
Specified Value	MB series		Inductance change: Within ±10%		
Specified Value	MB-H series		No significant abnormality in appearance.		
	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as sh				
Test Methods and	in below table.				
Remarks	Temperature	-40±2°C			
	Time	1000+24/-0 hour			
Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hr					

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20. High temperatur	re life test			
Specified Value	MB series		Inductance change : Within ±10%	
	MB-H series		No significant abnormality in appearance.	
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table.			
	Temperature	85±2°C		
	Time	1000+24/-0 hour		
	Recovery: At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.			
21. Loading at high	temperature life test			
Specified Value	MB series			
	MB-H series			
22. Standard condit	ion			
Specified Value	MB series		Standard test condition : Unless otherwise specified, temperature is 20±15°C and 65±20% of relative humidity.	
	MB-H series		When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of $20\pm2^{\circ}\text{C}$ of temperature, $65\pm5\%$ relative humidity. Inductance is in accordance with our measured value.	

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METAL WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ MB SERIES ∕ MCOIL™ MB-H SERIES)

PRECAUTIONS

1. Circuit Design

Precautions

1

◆Operating environment

1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.

2. PCB Design

Precautions

- **♦**Land pattern design
- 1. Please refer to a recommended land pattern.

Technical considerations

◆Land pattern design Surface Mounting

- Mounting and soldering conditions should be checked beforehand.
- · Applicable soldering process to this products is reflow soldering only.

3. Considerations for automatic placement

Precautions

- Adjustment of mounting machine
 - Excessive impact load should not be imposed on the products when mounting onto the PC boards.
- 2. Mounting and soldering conditions should be checked beforehand.

l echnical considerations

- Adjustment of mounting machine
 - 1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering

◆Reflow soldering

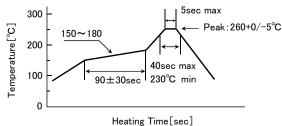
- 1. Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified.
- 2. The product shall be used reflow soldering only.

Precautions

- 3. Please do not add any stress to a product until it returns in normal temperature after reflow soldering.
- ♦Lead free soldering
 - 1. When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, soldering etc sufficiently.
- ◆Reflow soldering
 - 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

Recommended reflow condition (Pb free solder)

Technical considerations



5. Cleaning

Precautions

- ◆ Cleaning conditions
- 1. Washing by supersonic waves shall be avoided.

Technical considerations

♦Cleaning conditions

1. If washed by supersonic waves, the products might be broken.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

6. Handling ◆Handling 1. Keep the product away from all magnets and magnetic objects. ◆Breakaway PC boards (splitting along perforations) 1. When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆Mechanical considerations Precautions 1. Please do not give the product any excessive mechanical shocks. 2. Please do not add any shock and power to a product in transportation. ◆Pick-up pressure 1. Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part. ◆Packing 1. Please avoid accumulation of a packing box as much as possible. 1. There is a case that a characteristic varies with magnetic influence. ◆Breakaway PC boards (splitting along perforations) 1. The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs. ◆Mechanical considerations Technical 1. There is a case to be damaged by a mechanical shock. considerations 2. There is a case to be broken by the handling in transportation. ◆Pick-up pressure 1. Damage and a characteristic can vary with an excessive shock or stress. **♦**Packing 1. If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products.

7. Storage conditions				
Precautions	 ♦ Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. • Recommended conditions Ambient temperature : 0~40°C Humidity : Below 70% RH • The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within 6 months from the time of delivery. In case of storage over 6 months, solderability shall be checked before actual usage. 			
Technical considerations	◆Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.			